

2SK2769-01MR

FUJI POWER MOSFET

N-CHANNEL SILICON POWER MOSFET

FAP-2S Series

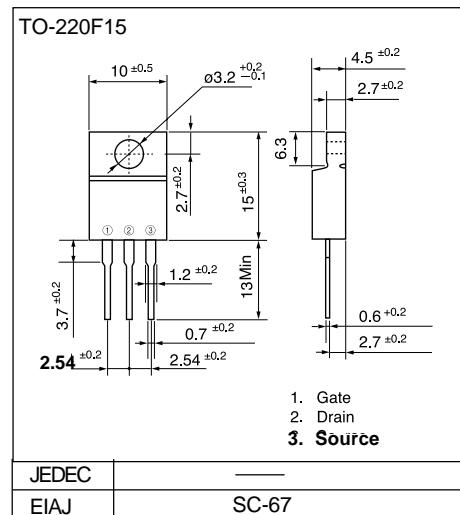
■ Features

- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- Avalanche-proof

■ Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

■ Outline Drawings



■ Maximum ratings and characteristic Absolute maximum ratings

● (Tc=25°C unless otherwise specified)

Item	Symbol	Ratings	Unit
Drain-source voltage	VDS	900	V
Continuous drain current	Id	±3.5	A
Pulsed drain current	Id(puls)	±14	A
Gate-source voltage	VGS	±35	V
Repetitive or non-repetitive	IAR *2	3.5	A
Maximum Avalanche Energy	EAS*1	111	mJ
Max. power dissipation	PD	40	W
Operating and storage temperature range	Tch	+150	°C
	Tstg	-55 to +150	°C

*1 L=16.6mH, Vcc=90V *2 Tch≤150°C

● Electrical characteristics (Tc =25°C unless otherwise specified)

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V(BR)DSS	Id=1mA Vgs=0V	900			V
Gate threshold voltage	VGS(th)	Id=1mA VDS=VGS	3.5	4.0	4.5	V
Zero gate voltage drain current	Idss	Vds=900V Vgs=0V	Tch=25°C Tch=125°C	10 0.2	500 1.0	μA mA
Gate-source leakage current	IGSS	Vgs=±35V Vds=0V		10	100	nA
Drain-source on-state resistance	RDS(on)	Id=2.0A Vgs=10V		4.0	5.5	Ω
Forward transconductance	gfs	Id=2.0A Vds=25V		1.0	2.0	S
Input capacitance	Ciss	Vds=25V		450	680	pF
Output capacitance	Coss	Vgs=0V		75	120	
Reverse transfer capacitance	Crss	f=1MHz		40	60	
Turn-on time ton	td(on)	Vcc=600V Id=3.5A		20	30	ns
	tr	Vgs=10V		40	60	
Turn-off time toff	td(off)	Rgs=10Ω		50	80	
	tf			25	40	
Avalanche capability	Iav	L=100 μH Tch=25°C	3.5			A
Diode forward on-voltage	VSD	If=2xIdR Vgs=0V Tch=25°C		1.0	1.5	V
Reverse recovery time	trr	If=IdR Vgs=0V		1000		ns
Reverse recovery charge	Qrr	-di/dt=100A/μs Tch=25°C		5.0		μC

● Thermal characteristics

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	Rth(ch-c)	channel to case			3.125	°C/W
	Rth(ch-a)	channel to ambient			62.5	°C/W

■ Characteristics

